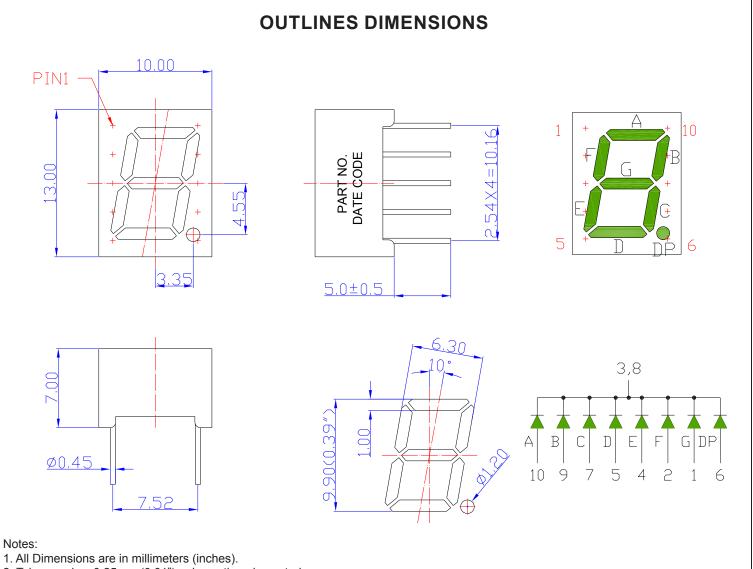


### SPECIFICATIONS

# CDSC39G2WBF



2. Tolerance is  $\pm$  0.25mm (0.01") unless otherwise noted.

3. Specifications are subject to change without notice.

Part Number		Chip Material	Color of Emission	Segment/Face	Description	
CDSC390	G2WBF	InGaAIP	Green	White/Black	Common Cathode	





### ABSOLUTE MAXIMUM RATINGS

#### (TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	85	mW			
Pulse Forward Current	lfp	120	mA			
Continuous Forward Current	lF	30	mA			
Reverse Voltage per dice	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width $\leq$ 10 ms, Duty Ratio $\leq$ 1/10. Soldering Condition: 260 °C/ 5sec						

# OPTICAL-ELECTRICAL CHARACTERISTICS

# (TA=25°C)

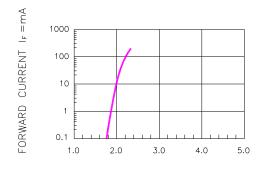
Deremeter	Symbol	Test Condition	Value			Lloit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	١v	l⊧ = 20mA	-	10	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	2.1	2.6	V
Reverse Leakage Current	lr	V <sub>R</sub> = 5V	-	-	10	μA
Peak Wavelength	λр	l⊧ = 20mA	-	573	-	nm
Dominant Wavelength	λd	l⊧ = 20mA	-	571	-	nm
Spectral Line half-width	Δλ	l⊧ = 20mA	-	20	-	nm

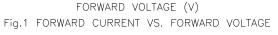


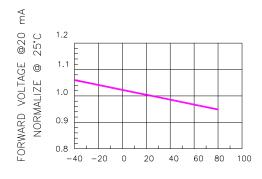


## **OPTICAL CHARACTERISTIC CURVES**

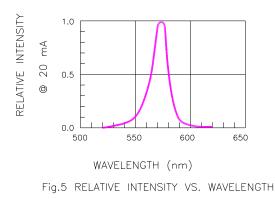
### (25 °C Free Air Temperature Unless Otherwise Specified)

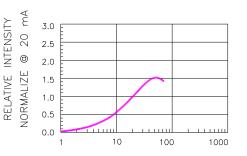






AMBIENT TEMPERATURE(°C) Fig.3 FORWARD VOLTAGE VS. TEMPERATURE





FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURREN

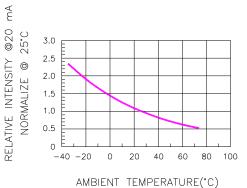
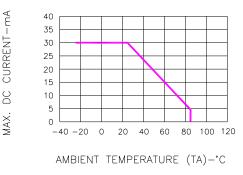
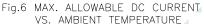


Fig.4 RELATIVE INTENSITY VS. TEMPERATUR



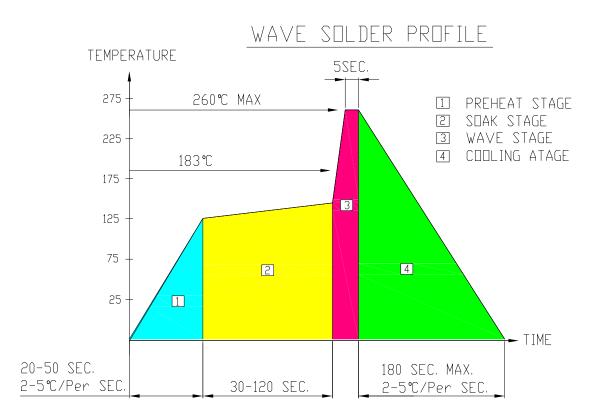






#### SOLDERING CONDITIONS – DISPLAY TYPE LED

### RECOMMEND SOLDERING PROFILE



#### SOLDERING IRON

Basic spec is  $\leq$ 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

#### REWORK

Customer must finish rework within ≦4 sec under 245°C.

